

Docket No.: 2336-086

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of

Jeong-Goo YOON et al

Serial No. Not yet assigned

Filed: herewith

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Group Art Unit: Not yet assigned

Examiner: N/A

For: PROCESS FOR LAPPING WAFER AND MEHOD FOR PROCESSING BACKSIDE
OF WAFER USING THE SAME

INFORMATION DISCLOSURE STATEMENT

Assistant Commissioner for Patents
Washington, D. C. 20231

Sir:

In accordance with the provisions of 37 C.F.R. 1.56, 1.97 and 1.98, the attention of the Patent and Trademark Office is hereby directed to the documents listed on the attached form PTO-1449. It is respectfully requested that the documents be expressly considered during the prosecution of this application, and that the documents be made of record therein and appear among the "References Cited" on any patent to issue therefrom.

This Information Disclosure Statement is being filed within three months of the U.S. filing date OR before the mailing date of a first Office Action on the merits. No certification or fee is required.

Respectfully submitted,

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PATENT

Hayes

